

New Project Proposal: SFF-TA-1016

Originally Presented: October 27, 2023 Updated Scope Presented: December 01, 2023 Editor: Paul Coddington [Amphenol] Supporters: Jason Stuhlsatz [Broadcom], Michael Gregoire [Dell], Glen Hanna [Lenovo], & Calbert Lo [Supermicro]

New Project Proposal: SFF-TA-1016, updates to Rev 1.1

- Due to changes in PCIe add-in card keep out zones, two 74 contact x8 right angle connectors with mating no antiskew side flange straight plugs will no longer fit along the short edge of a low-profile PCIe card. Alternatively, a 148 contact x16 right angle connector will still fit. However, the mating plugs with the anti-skew side flanges will violate the new keep out zones. So, a new no anti-skew side flange version of the plugs is needed.
 - Add a no flange version of the 148 contact plugs, just like was done previously for the 74 contact version plugs.
 - Since we are adding a no anti-skew side flange version for yet another size plug, we might as well add a no anti-skew side flange version to all the remaining sizes in order to possibly prevent the need for future revisions of this specification. So, we will add a no anti-skew side flange version for the 38 contact plugs and 124 contact plugs as well, in case they are ever required.

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Also, adding an EDSFF solution to the current configurations.

- Add E1 1C plug & mating vertical receptacle connector
- Add E3 1C plug, E3 2C plug, & mating vertical receptacle connector
- Editor: Paul Coddington
- Supporters:
 - 1. Amphenol
 - 2. Broadcom
 - 3. Dell
 - 4. Lenovo
 - 5. Supermicro



Sample changes to be made to the current 148 contact version plugs













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Mating Dimensions:

Mating with E1 1C plug





Board Connector Footprint:



RECOMMENDED PCB LAYOUT (GENERAL TOLERANCES :+/-0.05)



New Hybrid EDSFF Applications:













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Mating Dimensions:

Mating with E3 1C plug



Mating with E3 2C plug



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Board Connector Footprint:



RECOMMENDED PCB LAYOUT (GENERAL TOLERANCES :+/-0.05)



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IP Declaration:

 NOTE: The document will undergo a new IP disclosure period once published as a new Rev 1.2 per the SNIA SFF Process Guide

Optional: General timeline for project completion (estimates only)

- Initial Project Start Approval: October 27, 2023
- DRAFT Revision 1.1.1 by November 6, 2023
- Review Ballot end by December 7, 2023
- Expand scope of the project proposal: December 1, 2023
- DRAFT Revision 1.1.2 by December 4, 2023
- End current Review Ballot, Restart with the new DRAFT, & new Review Ballot to end by January 3, 2024?
- Comment Resolution & updated revision estimated by January 12, 2024
- Approval Ballot end estimated by February 14, 2024
- Comment Resolution & final Published revision estimated by February 23, 2024
- IP Declaration completed estimated by April 23, 2024?

